

# 1A, 50V - 1000V Fast Recovery Surface Mount Rectifier

### FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low profile package
- Low power loss, high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

# **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- General purpose

# **MECHANICAL DATA**

- Case: SOD-123FL
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 0.016g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I <sub>F</sub>	1	А			
V <sub>RRM</sub>	50 - 1000	V			
I <sub>FSM</sub>	30	А			
T <sub>J MAX</sub>	150	°C			
Package	SOD-123FL				
Configuration	Single die				





SOD-123FL



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)									
PARAMETER	SYMBOL	RS1A FL	RS1B FL	RS1D FL	RS1G FL	RS1J FL	RS1K FL	RS1M FL	UNIT
Marking code on the device		RAF	RBF	RDF	RGF	RJF	RKF	RMF	
Repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Forward current	I <sub>F</sub>	1					Α		
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30					А		
Junction temperature	TJ	- 55 to +150				°C			
Storage temperature	T <sub>STG</sub>	- 55 to +150			°C				



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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	ТҮР	UNIT			
Junction-to-lead thermal resistance	R <sub>eJL</sub>	17	°C/W			
Junction-to-ambient thermal resistance	R <sub>eJA</sub>	84	°C/W			
Junction-to-case thermal resistance	R <sub>eJC</sub>	19	°C/W			

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
		$I_F = 0.5A, T_J = 25^{\circ}C$		0.84	-	V
	RS1AFL RS1BFL	$I_F = 1.0A, T_J = 25^{\circ}C$	V <sub>F</sub>	0.91	1.05	V
	RS1DFL	$I_F = 0.5A, T_J = 125^{\circ}C$		0.70	-	V
<b>—</b> (1)	RS1FFL	$I_F = 1.0A, T_J = 125^{\circ}C$		0.78	0.90	V
Forward voltage <sup>(1)</sup>		$I_F = 0.5A, T_J = 25^{\circ}C$		0.97	-	V
	RS1JFL	$I_F = 1.0A, T_J = 25^{\circ}C$		1.04	1.30	V
	RS1KFL RS1MFL	I <sub>F</sub> = 0.5A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.80	-	V
		$I_F = 1.0A, T_J = 125^{\circ}C$		0.89	1.12	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		$T_J = 25^{\circ}C$		-	5	μA
		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	150	μA
Reverse recovery time	RS1AFL RS1BFL RS1DFL RS1FFL RS1FFL RS1GFL	I <sub>F</sub> = 0.5A , I <sub>R</sub> = 1.0A I <sub>rr</sub> = 0.25A	t <sub>rr</sub>	-	150	ns
	RS1JFL RS1KFL RS1MFL	1 <sub>m</sub> – 0.23A		-	250	ns
Junction capacitance	n capacitance RS1AFL RS1BFL RS1DFL RS1FFL RS1GFL	1MHz, V <sub>R</sub> = 4.0V	CJ	15	-	pF
	RS1JFL RS1KFL RS1MFL			11	-	pF

### Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING			
RS1xFL	SOD-123FL	10,000 / Tape & Reel			

Notes:

1. "x" defines voltage from 50V(RS1AFL) to 1000V(RS1MFL)



# **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

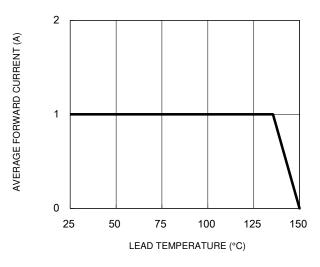
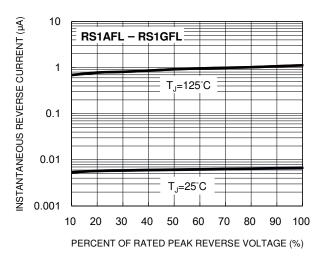
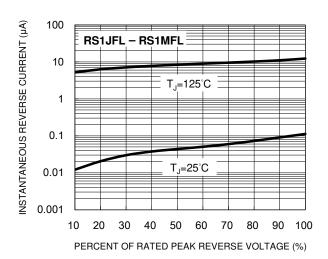


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

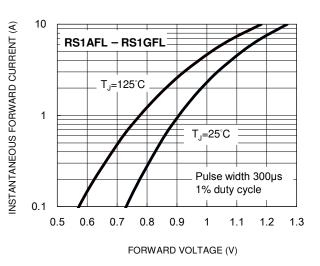






100 (La) 10 RS1JFL - RS1MFL 10 F=1.0MHz Vsig=50mVp-p 0.1 1 10 100 REVERSE VOLTAGE (V)

#### **Fig.4 Typical Forward Characteristics**



#### **Fig.6 Typical Forward Characteristics**

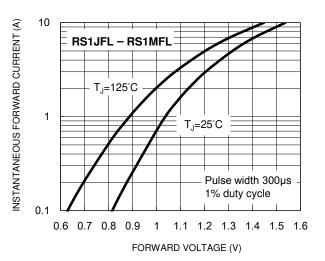


Fig.2 Typical Junction Capacitance

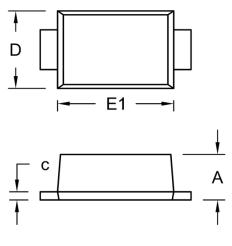
# RS1AFL - RS1MFL

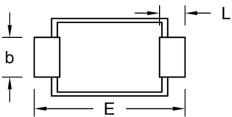
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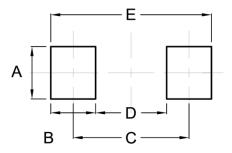
SOD-123FL





#### Unit (inch) Unit (mm) DIM. Min. Max. Max. Min. 1.35 0.053 А 0.88 0.035 b 0.80 1.15 0.031 0.045 0.10 0.30 0.004 0.012 С 2.10 D 1.70 0.067 0.083 Е 3.45 3.95 0.156 0.136 E1 2.60 3.10 0.102 0.122 L 0.90 0.035 0.30 0.012

# SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

# **MARKING DIAGRAM**



YW = Date Code

F = Factory Code



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